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EXCHANGE METHOD FOR SEMICONDUCTOR CHIP

INTERNATL BUSINESS MACH CORP <IBM>

Abstract:

PURPOSE: To easily exchange a facedown bonded resin-sealed semiconductor chip, without lowering reliability.

CONSTITUTION: A facedown bonded semiconductor chip 4, which is sealed with resin 14, is cut by a cutting end mill and removed from a substrate 2. Then the resin 14 and a bump electrode 16 left on the substrate 2 are ground by a finishing end mill to nearly a half as large as the original height and are thus flattened. Another chip 4A with a bump electrode 6A is positioned at a bump electrode 6 on the substrate 2 and bonded facedown. Lastly, resin 14A is supplied to the gap between the chip 4A and substrate 2 and the circumference of the chip 4A to be sealed.

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Patents Citing This One (3): US6274389 B1 20010814

Loctite (R&D) Ltd.

Mounting structure and mounting process from semiconductor devices

US6316528 B1 20011113 Loctite (R&D) Limited

Thermosetting resin compositions

US6605355 B1 20030812 Three Bond Co., Ltd.

Epoxy resin composition